

Appl. No. 10/552,186
Amdt. dated September 18, 2007
Reply to Office Action of April 19, 2007

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the applications:

Listing of Claims:

Claims 1& 2 (Previously Cancelled)

Claim 3 (Currently Amended) A small outline leadless package comprising:

- (a) a molding compound encapsulating discrete semiconductor devices comprising one of a solder contact bump small outline integrated circuit and a solder contact bump small outline transistor to form a package having a top, bottom, and four side surfaces;
- (b) a pair of electrical contacts each contacting a solder contact bump and extending to and flush with one of said surfaces;
- (c) each of said electrical contacts providing an exposed contact surface co-planar with said one of said surfaces and terminating at a junction between said one of said surfaces and another of said surfaces, each having longitudinally extending notches to provide mechanical attachment to the molding compound, said notches extending from one surface of the lead to an adjacent surface of the lead; and
- (d) the termination of said contacts occurring only at oppositely disposed package surfaces.

Appl. No. 10/552,186
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Claim 4 (previously amended) The combination set forth in claim 3 wherein the exposed contact surface of said electrical contacts is shaped to identify the electrical function of the encapsulated device.

Claim 5 (previously amended) The combination set forth in claim 3 wherein one of said electrical contacts is S-shaped for contacting solder bumps on a surface of said discrete semiconductor device and wherein a second electrical contact is planar and contacts solder contact bumps on an opposite side of said discrete semiconductor device.

Claims 6-7 (previously cancelled)

Claim 8 (original) A small outline leadless package comprising:

(a) a molding compound encapsulated discrete semiconductor device comprising one of a solder contact bump small outline integrated circuit and a solder contact bump small outline transistor to form a package having a top, bottom and four side surfaces;

(b) a pair of L-shaped electrical contacts having only one substantial bend, each of said contacts contacting a solder contact bump and extending to and flush with two of said package surfaces;

(c) said electrical contacts providing an exposed contact surface coplanar with each of said two package surfaces and terminating at a junction between said two package

Appl. No. 10/552,186
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surfaces; and

(d) the termination of said contacts occurring ~~only at~~ along oppositely disposed package surfaces.

Claim 9 (original) The small outline leadless package of claim 8 wherein said discrete semiconductor device is mounted between two vertically extending legs of opposing L-shaped electrical conductors.

Claim 10 (previously added) A small outline leadless package comprising:

(a) a molding compound encapsulating discrete semiconductor devices comprising one of a solder contact bump small outline integrated circuit and a solder contact bump small outline transistor to form a package having top, bottom and four side surfaces;

(b) a pair of electrical contacts each contacting a solder contact bump and extending to and flush with one of said surfaces;

(c) each of said electrical contacts providing an exposed contact surface co-planar with said one of said surfaces, each of said exposed contact surfaces shaped to identify an electrical function of the encapsulated device; and

(d) the termination of said contacts occurring only at oppositely disposed package surfaces.